

P-Ch MOSFET

General Description

The WSD45P04DN56 is the highest performance trench P-ch MOSFET with extreme high cell density, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The WSD45P04DN56 meet the RoHS and Green Product requirement,100% EAS guaranteed with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

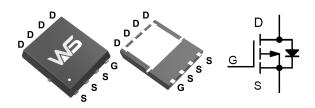
Product Summery

| BVDSS | RDSON | ID |
|-------|-------|------|
| -40V | 15mΩ | -45A |

Applications

- High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- Load Switch

DFN5X6_8L Pin Configuration



Absolute Maximum Ratings

| Symbol | Parameter | Rating | Units |
|--------------------------------------|--|------------|-------|
| V _{DS} | Drain-Source Voltage -40 | | V |
| V _{GS} | Gate-Source Voltage | ±20 | V |
| I _D @T _C =25℃ | Continuous Drain Current, -V _{GS} @ -10V ¹ | -45 | А |
| I _D @T _C =100℃ | Continuous Drain Current, -V _{GS} @ -10V ¹ | -23 | A |
| I _{DM} | Pulsed Drain Current ² | -120 | А |
| EAS | Single Pulse Avalanche Energy ³ | 125 | mJ |
| I _{AS} | Avalanche Current | -50 | А |
| P₀@T₀=25℃ | Total Power Dissipation ⁴ | 52 | W |
| T _{STG} | T _{STG} Storage Temperature Range -55 to 150 | | °C |
| TJ | Operating Junction Temperature Range | -55 to 150 | °C |

Thermal Data

| Symbol | Parameter | Тур. | Max. | Unit | |
|------------------|--|------|------|------|--|
| R _{θJA} | Thermal Resistance Junction-Ambient ¹ | | 62 | °C/W | |
| R _{θJC} | Thermal Resistance Junction-Case ¹ | | 2.4 | °C/W | |



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Electrical Characteristics (T_J=25 °C, unless otherwise noted)

| Symbol | Parameter | Conditions | Min. | Тур. | Max. | Unit |
|--|--|--|------|--------|------|------|
| BV _{DSS} | Drain-Source Breakdown Voltage | V _{GS} =0V , I _D =-250uA | -100 | | | V |
| $\triangle BV_{DSS} / \triangle T_{J}$ | BV _{DSS} Temperature Coefficient | Reference to 25 $^\circ\!\mathrm{C}$, I_D=-1mA | | -0.021 | | V/℃ |
| В | Static Drain-Source On-Resistance ² | V _{GS} =-10V , I _D =-30A | | 15 | 20 | mΩ |
| R _{DS(ON)} | | V _{GS} =-4.5V , I _D =-20A | | 18 | 25 | mΩ |
| V _{GS(th)} | Gate Threshold Voltage | | -1.2 | -1.6 | -2.5 | V |
| $	riangle V_{GS(th)}$ | V _{GS(th)} Temperature Coefficient | $V_{GS} - V_{DS}$, $I_D - 2500A$ | | 4.08 | | mV/℃ |
| le es | Drain Source Leekage Current | V _{DS} =-40V , V _{GS} =0V , T _J =25℃ | | | 1 | uA |
| I _{DSS} | Drain-Source Leakage Current | V_{DS} =-40V , V_{GS} =0V , T_{J} =55 $^{\circ}$ C | | | 5 | |
| I _{GSS} | Gate-Source Leakage Current | V_{GS} = $\pm20V$, V_{DS} = $0V$ | | | ±100 | nA |
| Qg | Total Gate Charge (-4.5V) | | | 20 | | |
| Q _{gs} | Gate-Source Charge | V _{DS} =-20V , V _{GS} =-10V , I _D =-12A | | 5.4 | | nC |
| Q _{gd} | Gate-Drain Charge | | | 5.2 | | 1 |
| T _{d(on)} | Turn-On Delay Time | | | 28 | | |
| Tr | Rise Time | V_{DD} =-20V , V_{GS} =-10V , | | 24 | | 20 |
| T _{d(off)} | Turn-Off Delay Time | R _G =3.3Ω, | | 70 | | ns |
| T _f | Fall Time | I _D =-1A ,RG=30Ω. | | 6.7 | | |
| C _{iss} | Input Capacitance | | | 2500 | | |
| C _{oss} | Output Capacitance | V _{DS} =-20V , V _{GS} =0V , f=1MHz | | 226 | | pF |
| C _{rss} | Reverse Transfer Capacitance | | | 155 | | |

Diode Characteristics

| Symbol | Parameter | Conditions | Min. | Тур. | Max. | Unit |
|----------|--|--|------|------|------|------|
| Is | Continuous Source Current ^{1,6} | $V_G = V_D = 0V$, Force Current | | | -40 | А |
| V_{SD} | Diode Forward Voltage ² | V _{GS} =0V , I _S =-1A , TJ=25℃ | | | -1.2 | V |

Note :

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper, t \leq 10 sec.

2.The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%

3. The EAS data shows Max. rating . The test condition is V_{DD} =-25V, V_{GS} =-10V, L=0.1mH, I_{AS} =-50A

4. The power dissipation is limited by 150°C junction temperature

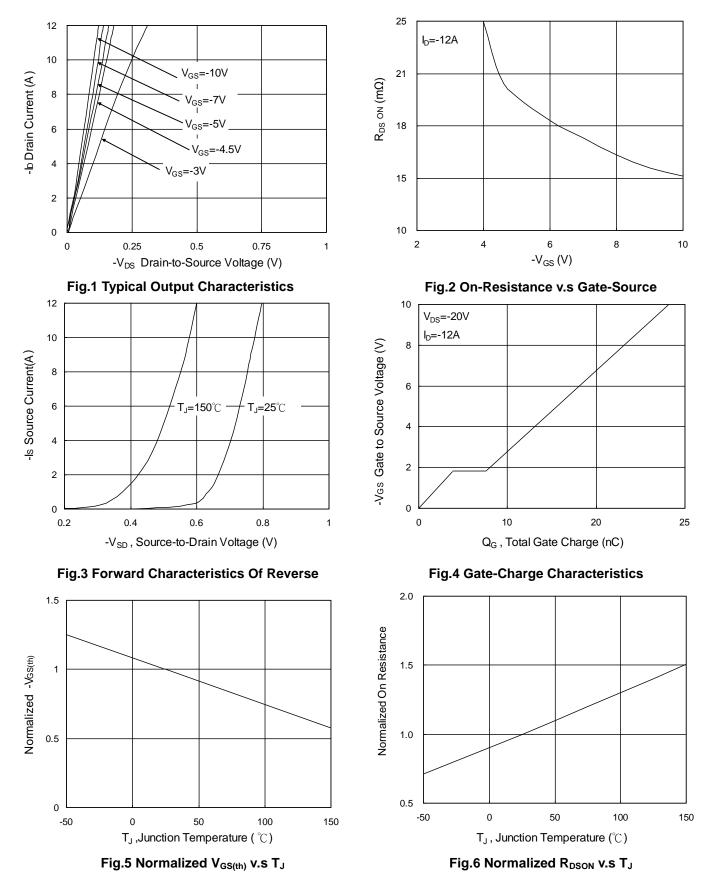
5. The Min. value is 100% EAS tested guarantee.

6. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



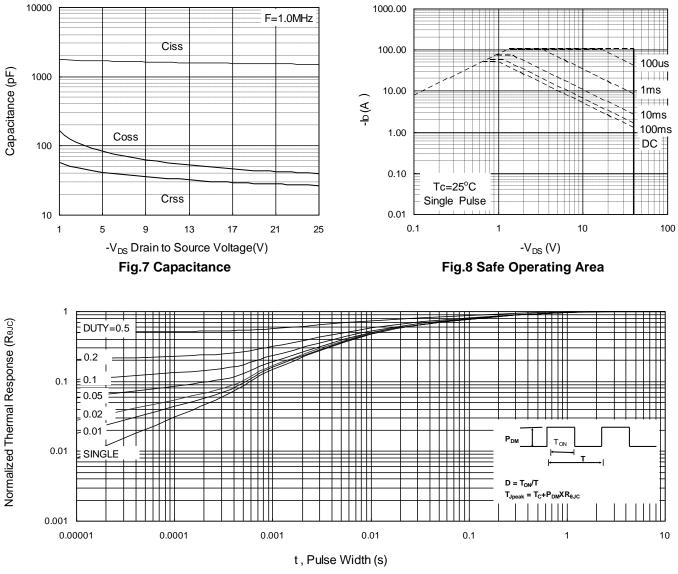
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Typical Characteristics

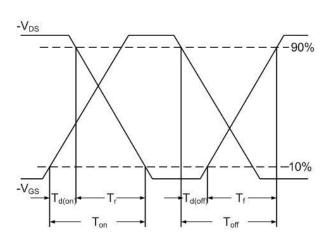


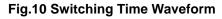


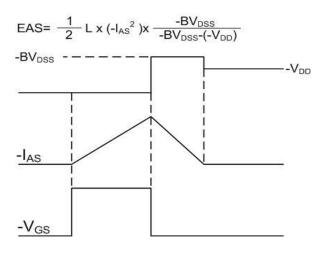
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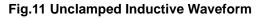














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